IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute					eous Materia	ials and Mfg Information				
Supplier	· Information														
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
nsemi												2023-06-08			
Contact Na	ame	Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-E	Env-Stewards	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com					
uthorized	d Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Versio	on 1	Manufacturing Site		1	Weight*	UOM	Unit Type
		FDMF8811 100V Smart Power		r Stage		2023-06-08	8 PBB			1	51.40115	mg	Each		
Ianufac	cturing Proccess Informa	ation													·
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-0		-STD-020 MSL	Rating	Peak Process Body Temperat		y Temperatur	ure Max Time at Peak Tempera		Temperat	ure Numbe	r of Reflow Cy	cles
Matte Tin (Sn) - annealed			CU Alloy 1				260 C 30					seconds 3			
omments															
vel 1 - ma	aximum time at peak temperat	ture during sol	ldering is 10-3	0 seconds											
or more i	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated diphenyls of an applicable quantity limit, please indication in the graph of an applicable quantity limit, please indications. Supplier acknowledges that Company will we relied on information provided by others in a minimum and the Supplier agrees that, at a minimum and the Supplier enter into a written agreem source of the Supplier's liability and the Company of the Supplier's liability and the Supplier's liability and the Supplier's liability and the Company of the Supplier's liability and the Supplier's liabi	J 2011/65/EU and implemented by the laws of the Eyl ethers (each a "RoHS restricted substance") in exate below which, if any, RoHS exemption you belie les in this form using appropriate methods to ensure rely on this certification in determining the complian completing this form, and that Supplier may not ha, its suppliers have provided certifications regarding tent with respect to the identified part, the terms and impany's remedies for issues that arise regarding info cable to such part shall apply.	cess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- unce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certifications conditions of that agreement, including any warr	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	42.0022	mg	Supplier	Zinc (Zn)	7440-66-6		0.0504	mg
			Supplier	Iron (Fe)	7439-89-6		1.0081	mg
			Supplier	Copper (Cu)	7440-50-8		40.9101	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0336	mg
Clip Attach	0.2	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.015	mg
			Supplier	Proprietary	Proprietary Data		0.013	mg
			Supplier	Bismaleimide	13676-54-5		0.056	mg
			Supplier	PTFE	9002-84-0		0.116	mg
Die	5.4	mg	Supplier	Silicon (Si)	7440-21-3		5.4	mg
Die Attach Solder	7.60012	mg	Supplier	Silver (Ag)	7440-22-4		0.19	mg
			A	Lead (Pb)	7439-92-1	7a	7.0301	mg
			Supplier	Tin (Sn)	7440-31-5		0.38	mg
Lead Frame	51.7993	mg	Supplier	Silver (Ag)	7440-22-4		2.59	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0622	mg
			Supplier	Iron (Fe)	7439-89-6		1.2432	mg
			Supplier	Copper (Cu)	7440-50-8		47.8626	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0414	mg
Mold Compound-Black	40.1995	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.613	mg
			Supplier	Carbon Black (C)	1333-86-4		0.201	mg
			Supplier	Silica (SiO2)	14464-46-1		35.3756	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.01	mg
Plating	4.1	mg	Supplier	Tin (Sn)	7440-31-5		4.1	mg
Wire Bond	0.10003	mg	Supplier	Palladium (Pd)	7440-05-3		0.0018	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0981	mg